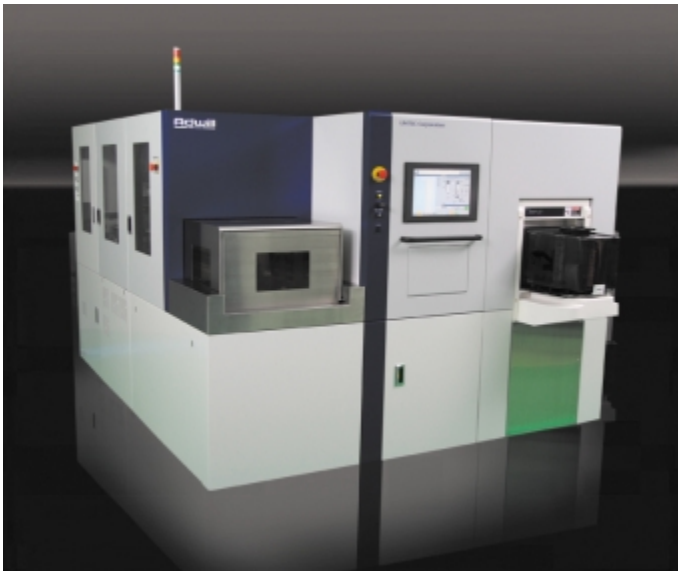


Fully-Automatic Vacuum Mounter

# RAD-2512F/12

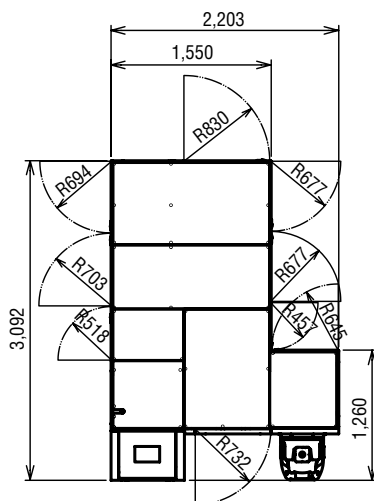


## Outline

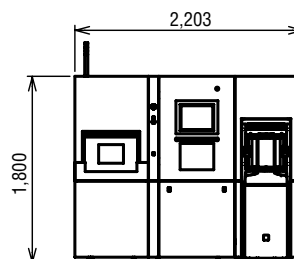
- Fully-automatic wafer mounter equipped with a pre-cut tape mounting function in a vacuum environment.
  - By using our unique vacuum control method, wafer mounting is performed without any contact with wafer surface.
  - By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.
- Options**
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
  - Vision System (Wafer ID Reader & Barcode Attachment System)
  - Dicing Tape In-line Pre-cutting

**Suitable Tape** ·Dicing tape: Adwill D series, G series

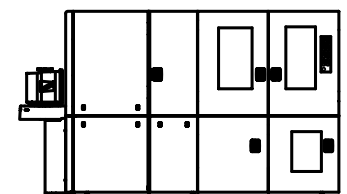
## External View



Top View



Front View



Right Side View

Unit:mm

## Facility

<b>Power Supply</b>	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 4.0kW
<b>Air Supply</b>	Air pressure	: 0.6-0.8MPa
	Air consumption	: >800L/min (ANR)
<b>Vacuum Supply (for workpiece) (for vacuum chamber)</b>	Vacuum pressure	: >-80kPa
	Ultimate Pressure	: 1.0Pa
	Pumping Speed	: >250L/min

**Applicable Wafer Size** 200mm (\*300mm currently in development)

**Size**

Width : 2,203mm  
Depth : 3,092mm  
Height : 1,800mm  
(excluding the signal tower and protruding parts)

**Weight** 2,600kg

**UPH** 20wafers/hour

The above processing capacity is based on following conditions:

Wafer	: 200mm diameter non-polished mirror wafer
Ring frame	: for 200mm wafer
Dicing tape	: D-184 from LINTEC



**LINTEC Corporation** *Linking your dreams*

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